

# REČEÍVED

DEC 1 7 2002

TC 1700

PATENT Serial No. 09/880,925 Docket No. 10517/102

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Koichi Hiramatsu, et al.

Serial No.

09/880,925

Filed

June 15, 2001

**Group Art Unit** 

1722

Examiner

unassigned

/For

MOLDING CLAMPING APPARATUS AND MOLD

CLAMPING METHOD

# CORRECTED INFORMATION DISCLOSURE STATEMENT

Commissioner of Patents and Trademarks Washington, D.C. 20231

Sir:

The Applicants have noted that the Information Disclosure Statement filed on October 7, 2002 contains an incorrect identification of a Japanese reference listed in the submitted European Search Report. A corrected copy of the Form 1449 reference listing is enclosed.

No fee is believed due in connection with this submission. Nonetheless, if any fee is required, the Commissioner is authorized to debit Deposit Account No. 11-0600. Two copies of this paper are attached.

Respectfully submitted,

**KENYON & KENYON** 

Date: December 16, 2002

Mark H. Neblett

Registration No. 42,028

#### ATTY. DOCKET NO. SERIAL NO. Form 1449 10517/102 09/880,925 **CORRECTED** INFORMATION DISCLOSURE **APPLICANT** Koichi HIRAMATSU et al. STATEMENT BY APPLICANT FILING DATE **GROUP** DEC 1 6 2002 2 Page 1/1 June 15, 2001 1277

## U. S. PATENT DOCUMENTS

EXAMINER INITIAL	PATENT NUMBER	PATENT DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,600,983	02/11/1997	D.R. Rigsby			
	5,582,052	12/10/1996	D.R. Rigsby			
	5,755,653	05/26/1998	K. Nishida	RI	- C	
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	6,041,633	03/28/2000	P. Bieling	7	C 1 7 2002	
				TC	1700	

## FOREIGN PATENT DOCUMENTS

		,				TRAN	SLATION
EXAMINER INITIAL	DOCUMENT NUMBER	DATE*	COUNTRY	CLASS	SUBCLASS	YES	NO
	0 808 674	11/26/97	EP				X

<sup>\*</sup> Publication date, unless otherwise indicated

### OTHER DOCUMENTS

EXAMINER INITIAL	 AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.
	European Search Report (two pages), dated September 20, 2002, with Annex (two pages), European Patent Application No. 01114484.7, corresponding to this application.
	Patent Abstracts of Japan, abstract (in English) of JP 05 329693A.

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